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10/596,088	05/30/2006	Tokumi Kobayashi	P30048	1724
52123 7590 08/17/2009 GREENBLUM & BERNSTEIN, P.L.C.			EXAMINER	
1950 ROLANI	O CLARKE PLACE	·.	RAO, SHEELA S	
RESTON, VA	20191		ART UNIT	PAPER NUMBER
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			08/17/2009	ELECTRONIC

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

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Application No. Applicant(s) 10/596.088 KOBAYASHI, TOKUMI Office Action Summary Examiner Art Unit Sheela Rao 2123 -- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --Period for Reply A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS. WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION. Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). Status 1) Responsive to communication(s) filed on 26 May 2009. 2a) This action is FINAL. 2b) This action is non-final. 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213. Disposition of Claims 4)\(\times\) Claim(s) 24.25.27-30.32.33.35.36.38.40.41 and 45-53 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) _____ is/are allowed. 6) Claim(s) 24.25.27-30.32.33.35.36.38.40.41 and 45-53 is/are rejected. 7) Claim(s) _____ is/are objected to. 8) Claim(s) _____ are subject to restriction and/or election requirement. Application Papers 9) The specification is objected to by the Examiner. 10) The drawing(s) filed on is/are; a) accepted or b) objected to by the Examiner. Applicant may not request that any objection to the drawing(s) be held in abevance. See 37 CFR 1.85(a). Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152. Priority under 35 U.S.C. § 119 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. Attachment(s) 1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413) Paper No(s)/Mail Date. Notice of Draftsparson's Catent Drawing Review (CTO-948)

Information Disclosure Statement(s) (PTO/SB/08)
 Paper No(s)/Mail Date _______

5) Notice of Informal Patent Application

6) Other:

DETAILED ACTION

- This Office action is in response to papers filed on 26 May 2009.
- Claims 24-25, 27-30, 32-33, 35-36, 38, 40-41 and 45-53 are pending and presented for examination. Claims 23, 26, 31, 34, 37, 39 and 42-44 have been cancelled and claims 45-53 have been added.

Response to Amendment

- Acknowledgment is made of applicant's claim for foreign priority under 35
 U.S.C. 119(a)-(d). Receipt is acknowledged of papers submitted under 35
 U.S.C. 119(a)-(d), which papers have been placed of record in the file.
- The rejection of claims 23, 26, and 31 under 35 USC §112, second paragraph, is withdrawn in light of the amendments made.
- The rejection of claims 23-27, 31-32, 34, 36-38, 42 and 44 under 35 USC §102(e) as being anticipated by US Patent Application Publication No. US 2001/0021265 A1 to Wilson et al. is withdrawn in light of the amendments made.
- 6. The rejection of claims 28-30, 33, 35, 39-41 and 43 are rejected under 35 USC §103(a) as being unpatentable over US Patent Application Publication No. US 2001/0021265 A1 to Wilson et al. in view of US Patent Application Publication No. US 2002/0103563 A1 to Izawa et al. is withdrawn in light of the amendments made.

Claim Rejections - 35 USC § 103

- The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.
- Claims 24-25, 27, 32, 36, 38, 45-49, 51 and 53 are rejected under 35 U.S.C.
 103(a) as being unpatentable over US Patent Application Publication No. US
 2001/0021265 A1 to Wilson et al. in view of US Patent No. US 6,555,400 B2 to
 Farnworth et al.

The reference of prior art by Wilson et al. (hereinafter referred to as "Wilson") teaches of a method for assembling integrated circuit devices which includes the elements of the instant invention as stated herewith.

Claims 45, 46, 47, 48, 49, 51 and 53 are directed to a circuit substrate production method or system that comprise the production of a multi-piece substrate which includes a plurality of substrate pieces, wherein the multi-piece substrate is separated into a plurality of pieces at one or each of a plurality of separation levels (taught by Wilson in paragraph [0008] wherein dicing of the wafers is explained); the multi-piece substrate includes an information recording portion that includes information related to the multi-piece substrate, wherein each sheet is configured with an information recording portion that includes information related to the entire substrate and information related to the identification of the substrate sheet and where each substrate piece is configured with an information recording portion that includes information related to the entire multi-piece substrate, to a substrate sheet and piece; recording on the information recording portions referenceable management and manufacturing

information related to the substrate manufacturer and the mounting manufacturer; and delivering the multi-piece substrate board to the mounting manufacturer. Wilson teach updateable and storable information regarding identification, management and manufacturing of the substrates in paragraph [0033] and in paragraphs [0020-0023] how the information is recorded and updated throughout the assembly process is explained. With regard to the limitations of the recording means and read-out means as claimed by claim 47. Wilson teaches the use of bar codes or OCR codes for recording the identification information and uses bar code readers and/or OCR code readers for reading the stored information in paragraph [0037]. Although the reference of prior art by Wilson teaches much of the limitations of the instant invention, Wilson fails to specifically point out the information in the information recording portion as being configured with information related to the substrate, sheet, and piece; for this reason the prior art of Farnworth et al. (hereinafter referred to as "Farnworth") is relied upon. Farnworth teaches of a method and apparatus that maintains structural integrity of a mounting substrate by the use of a designator that contains encoded information and is included on the mounting substrate assembly, see lines 6-67 of column 7. As for the recording of referenceable management and manufacturing information. Farnworth teaches of an electronic file that includes identification and mapped information of the substrate and each die site including manufacturing information, place of manufacture. etc. as explained in lines 18-32 in column 7 and lines 1-6 of column 9. With regard to the delivery of the substrate board to the mounting manufacturer, Farnworth teaches transporting the substrate to other stations in column 8 at lines 1-10. The stations as

taught by Farnworth can be interpreted as other areas or manufacturers since each station as described by Farnworth is responsible for a different task. It would have been obvious to one of ordinary skill in the art at the time the invention was made to have included the information recording portions of Farnworth with the IC device assembly method of Wilson so as to have an efficient, simple and automated way of accessing and storing information regarding each substrate at any time during the manufacture of such as stated by Farnworth in column 6, lines 44-51.

Claim 24 requires the information to be recorded as a two-dimensional code on the information recording portions. Wilson teaches this in paragraph [0023] wherein the use of optically-readable code, a two-dimensional code, is stated.

Claims 25, 32, 36, and 38 cite that in addition to the identification information of each of the substrates themselves, information related to a production step at the substrate manufacturer and information related to a production step at the mounting manufacturer are recorded on the information recording portions at the substrate manufacturer. In paragraph [0038], information related to the equipment and the substrates are stated as being included in the identification information.

Claim 27 is directed to the mounting of the substrate, specifically, at the mounting manufacturer, substrate mounting is performed based on the information which is read from the information recording portions and is related to the production step. Wilson teaches the mounting process as the die attach step in paragraph [0035].

9. Claims 28-30, 33, 35, 40-41, 50 and 52 are rejected under 35 U.S.C. 103(a) as being unpatentable over US Patent Application Publication No. US 2001/0021265 A1 to Wilson et al. in view of US Patent No. US 6,555,400 B2 to Farnworth et al., as applied to claims 45-49, 51 and 53, further in view of US Patent Application Publication No. US 2002/0103563 A1 to Izawa et al.

The limitations as taught by Wilson and Farnworth are stated heretofore.

Claims 50, 28, and 41 include the elements of claim 45 and further include a transmitting production information and identification information step wherein production step information about each of the substrates and the identification information read from the information recording portions are combined in the substrate manufacturer and the mounting manufacturer, are transmitted to a data processing center connected via a communication network, and are data-processed in the data processing center to thereby construct various databases, and wherein the substrate manufacturer and the mounting manufacturer perform required processing by retrieving required data from the databases via the communication network. The prior arts of Wilson and/or Farnworth teach the elements of the claimed limitations as aforementioned but fall short of teaching the information being transmitted to a data processing center via a communications network. As shown in Figs. 1 and 6 and stated in the abstract, the reference of Izawa et al. (hereinafter referred to as "Izawa") teach a computer environment is used wherein a database stores processing conditions and the computers of the equipment and manufacturers are able to communicate over a communication network. It would have been obvious to one of ordinary skill in the art at

the time the invention was made to have used network communication capabilities as per Izawa with the method and system of Wilson/Farnworth so as to enable direct transmission of data and information in a more efficient manner and to provide information automatically as stated in the abstract of Izawa.

Claims 29 and 33 further defines the steps of claims 46 and 47, wherein production step information about each of the substrates and the identification information read from the information recording portions are combined in the substrate manufacturer and the mounting manufacturer, are transmitted to a data processing center connected via a communication network, and are data-processed in the data processing center to thereby construct various databases, and wherein the substrate manufacturer and the mounting manufacturer perform required processing by retrieving required data from the databases via the communication network. The prior arts of Wilson and Farnworth teach the elements of the claimed limitations as aforementioned but fails to teach the information being processed by a data processing center and having the ability to build other databases. As stated in paragraphs [0017] and [0050], Izawa teaches a computer environment wherein a database is used and it is well known that numerous databases can be built to store and retrieve a variety of data processing conditions. It would have been obvious to one of ordinary skill in the art at the time the invention was made to have used multiple databases as is well known with the inventions of Wilson, Farnworth and Izawa so as to increase the ability of collecting more information and to provide the information automatically as stated in paragraph [0050] of Izawa.

Claims 30, 35, and 40 state the databases contain information about production histories at both the substrate manufacturer and the mounting manufacturer. Izawa teaches the use of production histories as described in the abstract and paragraph [0049].

Claim 52 is directed to a circuit substrate production method in which a substrate produced by a substrate manufacturer is delivered to a subsequent mounting manufacturer for mounting a component at the mounting manufacturer to thereby produce a circuit substrate, wherein when the substrate manufacturer records identification information on a substrate, which has an information recording portion configured such that identification information containing information related to management and manufacturing in each of the manufacturers is referenceable and recordable, and delivers the substrate to the mounting manufacturer, production step information related to the substrate and the identification information read from said information recording portion are combined at the substrate manufacturer and the mounting manufacturer, are transmitted to a data processing center connected via a communication network, and are data-processed in the data processing center to thereby construct various databases, and in that the substrate manufacturer and the mounting manufacturer perform required processing by retrieving required data from the databases via the communication network. The limitations of claim 52 are parallel to that of claim 45 as taught above. In addition, claim 52 includes the limitations of claim 28 wherein the production information being transmitted to a data processing center via a communication network is stated. However, the prior arts of Wilson and Farnworth

teach the elements of the claimed limitations as aforementioned but fail to teach the information being transmitted to a data processing center via a communications network. As shown in Figs. 1 and 6 and stated in the abstract, the reference of Izawa et al. (hereinafter "Izawa") teach a computer environment is used wherein a database stores processing conditions and the computers of the equipment and manufacturers are able to communicate over a communication network. It would have been obvious to one of ordinary skill in the art at the time the invention was made to have used network communication capabilities as per Izawa with the method and system of Wilson/Farnworth so as to enable direct transmission of data and information in a more efficient manner and to provide information automatically as stated in the abstract of Izawa.

Response to Arguments

10. Applicant's arguments, filed May 26, 2009, with respect to the rejection(s) of claim(s) 23-44 under 35 USC §102(e) and §103(a) have been fully considered and are persuasive. Therefore, the rejection has been withdrawn and Applicant's arguments are moot. However, upon further consideration, a new ground(s) of rejection is made as stated above.

Conclusion

 Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, THIS ACTION IS MADE FINAL. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

12. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Sheela Rao whose telephone number is (571) 272-3751. The examiner can normally be reached Monday - Wednesday from 9:00 am to 3:00 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Paul Rodriguez, can be reached on (571) 272-3753. The fax number for the organization where this application or any proceeding papers has been assigned is (571) 273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. It should be noted that status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-

direct.uspto.gov. Should any questions arise regarding access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Sheela Rao/ Examiner, Art Unit 2123 August 12, 2009

/Kidest Bahta/ Primary Examiner, Art Unit 2123